

PCN Number:	20160714001	PCN Date:	07/15/2016
Title:	Carrier Tape Change for select DSBGA Package Device		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	10/15/2016		
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Part number change
<input type="checkbox"/>		<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

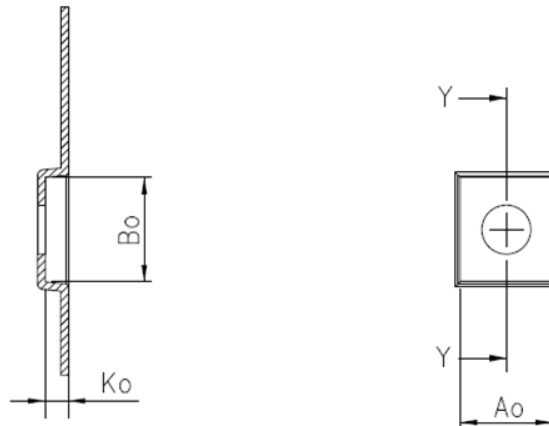
PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of a new carrier tape for select DSBGA Package Device. The material composition between the 2 carrier tapes is the same. A dimensional comparison summary is below:

Carrier tape Dimensions:

Dimension	From	To
Part No.	8008461-0001	4212589-0039
Ao	3.06 (+/- 0.05) mm	3.06 (+/- 0.05) mm
Bo	3.20 (+/- 0.05) mm	3.20 (+/- 0.05) mm
Ko	0.71 (+/- 0.05) mm	0.90 (+/- 0.05) mm



SECTION Y-Y
SCALE 4.5 : 1

Reason for Change:

Eliminate units being dislodged from the carrier tape pocket during SMT process

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

New Carrier Tape design

Product Affected:

LP875484YFQR	LP875494YFQR
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Qualification Report



Revision: B

EQ# :
A/T Site: TIEM

WCSP Carrier Tape Qualification Summary

Reference (QSS 003-008, 007-102, 009-006, 014-102)

Supplier:	<u>CPAK</u>
Vendor Part No:	<u>BD0285X0299 CF25 17X10G4 L300 W12</u>
TI Part No:	<u>4212589-0039</u> (If available)
Weight/meter (g):	<u>NA</u>
Material:	<u>Polycarbonate (PC)</u>
Package Description	<u>DSBGA</u>
Package Designator:	<u>49YFQ</u>
Result:	<u>Pass</u>
Date:	<u>May 9, 2016</u>

I. First Article Inspection Test	<u>Pass</u>	(Pass/Fail)
II. Manufacturability Test	<u>Pass</u>	
III. Dimensional Test	<u>Pass</u>	
IV. Camber Test	<u>Pass</u>	
V. Surface Resistivity Test	<u>Pass</u>	
VI. Fit Analysis	<u>Pass</u>	
VII. Drop Test	<u>Pass</u>	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com